



EV Group achieves die-to-wafer fusion and hybrid bonding milestone with 100 die transfer yield on multi-die 3D SoC – July 12, 2022



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Global sales of total semiconductor manufacturing equipment by original equipment manufacturers are forecast to reach a record \$117.5 billion in 2022. [More>>](#)



Tech News

EV Group achieves die-to-wafer fusion and hybrid bonding milestone with 100 die transfer yield on multi-die 3D SoC

EV Group (EVG) today announced it has achieved a major breakthrough in die-to-wafer (D2W) fusion and hybrid bonding by successfully demonstrating 100-percent void-free bonding yield of multiple die of different sizes from a complete 3D system-on-a-chip (SoC) in a single transfer process using EVG's GEMINI FB automated hybrid bonding system. [More>>](#)

ClassOne Technology announces new surface preparation technologies that extend the Solstice single-wafer platform

ClassOne Technology, a global provider of advanced electroplating and wet processing tools for microelectronics manufacturing, today announced it has expanded its flagship Solstice automated single-wafer platform with a suite of surface preparation (SP) technologies. [More>>](#)

Quantum Brilliance advances quantum computing development with NVIDIA

Quantum Brilliance has announced a collaboration with NVIDIA to accelerate the

development of the world's first hybrid quantum-classical computing platform. [More>>](#)

FEATURED PRODUCT

Fast Leak Detection

The Pfeiffer Vacuum ASM 390 / ASM 392 dry, mobile leak detectors are optimized for rapid pump downs and short response times. They offer high sensitivity for ultra-clean maintenance of large test chambers. Semi S2 compliant, the ASM 390 / ASM 392 offer rugged and reliable use and an ergonomic platform. [Learn more.](#)

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Featured Video

EMD Electronics' Digital Solutions organization focuses on leveraging data in R&D, quality, and supply chain to solve industry challenges and accelerate learning cycles. Customers can proactively identify the parameters that matter for their fab performance before excursions occur. They can also gain better control of newly identified parameters to improve the performance of materials in their fabs, which can contribute to yield optimization. The learnings are also useful in R&D for

new material innovation which accelerates the ramp up of next generation technology nodes. Watch this video interview with **Kutup Kurt, Head of Operations, Digital Solutions at EMD Electronics** to learn more.



44th EOS/ESD Symposium, September 18 – 23, 2022 at the Peppermill in Reno, NV

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Business News

Accellera Systems Initiative honors Lynn Garibaldi with 2022 Leadership Award

Garibaldi is recognized for 30 years of service and achievements since the founding of the Accellera standards organization. [More>>](#)

Lam Research, Entegris, Gelest team up to advance EUV dry resist technology ecosystem

Collaboration provides robust chemical supply chain for global chipmakers using the breakthrough technology and supports R&D for next-generation EUV applications. [More>>](#)

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The Need for Accredited Calibration for Compliance to IATF 16949

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